【Configuration】

Main system

1)Main frame with system controller

2) Carrier station

- Type: Foup Cassette Type - 3 Cassette
- Uni-cassette system

3) Coater unit

- 6 dispense nozzle with temperature controlled lines for etch unit
- RDS Pump (Millipore)
- Rinse nozzle : back/ EBR / solvent bath for etch unit
- Rinse system : 3 liter 2Tank Buffer tank system
- Degassing system.
- Programmable side rinse
  for PR nozzle(1, 2, 3, 4, 5, 6) - 36 bottles(1 bottle/1nozzle) in machine for unit
  for Thinner supply - CCSS
- AMC Suck-back valve - Drain: Direct drain

4) Developer unit

- H nozzle(1ea) for each unit
- 1 stream nozzle for DI rinse and 2 points for back side rinse on each unit
- Developer system : 3 liter 2Tank Buffer tank system
- Developer supply: CCSS - Degassing system
- Developer temperature control system - Drain: direct drain

5) I/F Wafer Stage Type : NIKON Type(SF13)

6) Adhesion Unit 1EA

- 100% sealing closed chamber(Built-in hot plate)
- HMDS tank with float sensor in system - HMDS supply : Local bottle

7) Low Temp Hot Plates (LHP) 5EA

8) Chill Plates (CPL) 4EA

9) Precision Chilling Hot Plates (CHP) 4EA

10) TCP Unit 1EA

11) TRS Unit 2EA

12) WEE (wafer edge exposure) unit 1EA

- UV Sensor : I-line

13) Chemical Cabinet : Solvent , HMDS , DEV Chemical Cabinet

14) Temperature&Humidity controller

- Type: Shinwa Series (ESA-8)

15) TEMP Control Unit(TCU) 1EA

16) AC Power Box